

WHAT IS CLAIMED:

Sub
A1

✓ 1. A method of forming a thin film comprising the step of: forming an AgPd alloy thin film using a sputtering target material, wherein the AgPd alloy thin film comprises Pd in an amount ranging from 0.5 to 4.9 atomic %.

✓ 2. The method of claim 1 wherein the alloy further comprises at least one of Cu or Cr in an amount ranging from 0.1 to 3.5 atomic %.

3. A thin film comprising:
an AgPd alloy comprising Pd in an amount ranging from 0.5 to 4.9 atomic %.

4. The thin film of claim 3 further comprising at least one of Cu or Cr in an amount ranging from 0.1 to 3.5 atomic %.

5. An optical recording medium comprising:
a thin film formed by using an AgPd alloy comprising Pd in an amount ranging from 0.5 to 4.9 atomic %.

6. The optical recording medium of claim 5 wherein the AgPd alloy further comprises at least one of Cu or Cr in an amount ranging from 0.1 to 3.5 atomic %.

Sub A2

✓ 7. A method of forming a thin film comprising the step of:
forming an AgPdTi alloy thin film using a sputtering target
material wherein the AgPdTi alloy comprises Pd in an amount ranging
from 0.1 to 1.5 atomic % and Ti in an amount ranging from 0.1 to
2.9 atomic %.

8. A thin film comprising:
an AgPdTi alloy comprising Pd in an amount ranging from 0.1 to
1.5 atomic % and Ti in an amount ranging from 0.1 to 2.9 atomic %.

9. An optical recording medium comprising:
a thin film comprising an AgPdTi alloy comprising Pd in an
amount ranging from 0.1 to 1.5 atomic % and Ti in an amount ranging
from 0.1 to 2.9 atomic %.

Add A3

Add C'